

TGP7500C Thermal Conductive Gap Filler Pad

BENEFITS AND FEATURES

- High thermal performance
- Ultra-high compressibility for low stress applications
- Excellent surface wetting for low contact resistance
- High reliability
- Electrically insulating

TYPICAL APPLICATIONS

- Consumer electronics
- Telecommunications & network servers
- Automotive electronics
- Power devices & modules
- Semiconductors logics & memory

OVERVIEW

Honeywell TGP7500C Thermal Conductive Gap Pad provides high thermal performance with ease of use across multitude of applications. Its ultra-high compressibility enables low stress and excellent conformity to mating surfaces. It is designed to minimize thermal resistance at interfaces and maintain excellent performance through reliability testing. Products are available in thickness range from 0.5mm to 5.0mm.

STORAGE & USE

- Shelf life 12 months at 0-35°C,
≤65% RH

Product Name	TGP7500C	Test Method
Color	Brick Red	Visual
Thickness (mm) ^{1*}	0.5-5	ASTM D374
Density (g/cm ³)	3.5	ASTM D792
Hardness (Shore00)	20	ASTM D2240
Thermal Conductivity (W/m·K)	7.5	ASTM D5470
Thermal Impedance (°C ·in ² /W) (1mm@10psi, Typical Value)	0.16	ASTM D5470
Outgassing TML(%)	0.19	ASTM E595
Outgassing CVCM(%)	0.03	ASTM E595
Dielectric Constant@1MHz	8.1	ASTM D150
Dielectric strength (KV/mm)	7	ASTM D149
Volume Resistivity (ohm-cm)	1.0x10 ¹⁴	ASTM D257
Flammability Rating	V-0	UL94
Operating Temperature (°C)	-40~150	HON Internal

Typical property data value should not be used as specification

^{1*}Thickness range: 0.5-5.0mm with 0.25mm incremental

Thickness Tolerance: >=1mm, ±10%
0.5-1mm, ±0.1mm

Honeywell Electronic Materials

USA: 1-509-252-2102
China: 400-840-2233
Germany: 49-5137-999-9199
Japan: 81-3-6730-7092
Korea: 82-2-3483-5076
Singapore: 65-6580-3593

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